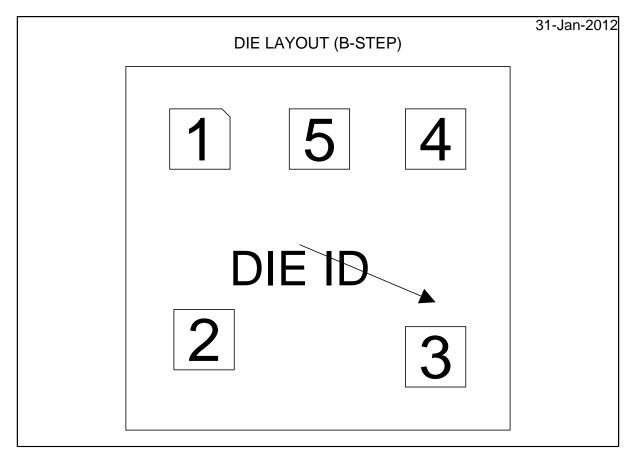


LMV7239 MWC 45NS,ULTRA LOW POWER, LOW VOLTAGE,RAIL-TO-RAIL INPUT



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information		
Physical Die	LMV7239B	Bond Pad Opening	75.84µm x 75.84µm	
Identification		Size (min)		
Die Step	В	Bond Pad Metalization	AL 0.5%CU	
Physical Attributes		Passivation	PECVDOX NITRIDE	
Wafer Diameter	203.2mm	Back Side Metal	BAREBACK	
Die Size (Drawn)	457.20µm x 482.60µm	Back Side Connection	VCC	
	18.0mils x 19.0mils			
Thickness	216µm Nominal			
Min Pitch	252.16µm			
Note: All values are roun	ded to the nearest micron			
Special Assembly Requir	ements:			
1				



LMV7239 MWC 45NS,ULTRA LOW POWER, LOW VOLTAGE,RAIL-TO-RAIL INPUT

(Referenced to	Die Bond Pad Coord o die center, coordinates in		· · · · ·	U. = Not Us	ed	
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
-		Х	Y	Х		Y
VOUT	1	-148.48	137.36	75.84	Х	75.84
V+	2	-143.20	-114.80	75.84	х	75.84
INPUT-	3	147.84	-136.40	75.84	х	75.84
INPUT+	4	147.84	137.36	75.84	х	75.84
V-	5	1.84	137.36	75.84	х	75.84



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